

Amendments to the claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

Claims 1-5 (canceled)

Claim 6 (currently amended): A BGA (ball grid array) package, which comprises:

- (a) a substrate having a front side and a back side;
- (b) a semiconductor chip mounted on the front side of the substrate, the semiconductor chip having an array of bond pads;
- (c) an array of solder balls implanted on the back side of the substrate;
- (d) an array of bond fingers provided beside the semiconductor chip and which are electrically connected to the bond pads on the semiconductor chip by a plurality of first bonding wires;
- (e) an array of electrically-conductive vias, each penetrating from the front side to the back side of the substrate and electrically connected to one of the solder balls;
- (f) a plurality of continuous electrically-conductive traces for electrically connecting a first subgroup of the bond fingers to corresponding ones of the vias, these continuous electrically-conductive traces including at least one being interposed between a second subgroup of the bond fingers and their corresponding vias; and
- (g) an electrically-conductive bridge as a second bonding wire that is mounted to span in an overhead manner across the interposing electrically-conductive trace such that the second bonding wire is free of interference with the interposing electrically-conductive trace and is free of interference with the first bonding wires, and an unfilled gap is formed between the second bonding wire and the interposing electrically-conductive trace, wherein the second bonding wire has one end electrically connected to the corresponding via and the other end electrically connected to the corresponding bond finger, and a top position of the second bonding wire is lower in height than a top position of the first bonding wires.

Claim 7 (canceled)

Claim 8 (previously presented): The BGA package of claim 6, wherein at least one of the first and second bonding wires is a gold wire.

Claims 9-10 (canceled)

Claim 11 (currently amended): A BGA (ball grid array) package, which comprises:

- (a) a substrate having a front side and a back side;
- (b) a semiconductor chip mounted on the front side of the substrate, the semiconductor chip having an array of bond pads;
- (c) an array of solder balls implanted on the back side of the substrate;
- (d) an array of bond fingers provided beside the semiconductor chip and which are electrically connected to the bond pads on the semiconductor chip by a plurality of bonding wires;
- (e) an array of electrically-conductive vias, each penetrating from the front side to the back side of the substrate and electrically connected to one of the solder balls;
- (f) a plurality of continuous electrically-conductive traces for electrically connecting a first subgroup of the bond fingers to corresponding ones of the vias, these continuous electrically-conductive traces including at least one being interposed between a second subgroup of the bond fingers and their corresponding vias; and
- (g) an electrically-conductive bridge as a zero-resistance chip resistor that is mounted to span in an overhead manner across the interposing electrically-conductive trace such that the chip resistor is free of interference with the interposing electrically-conductive trace and an unfilled gap is formed between the chip resistor and the interposing electrically-conductive trace, wherein the chip resistor has one end electrically connected to the corresponding via and the other end electrically connected to the corresponding bond finger, and a top position of the chip resistor is lower in height than a top position of the bonding wires.

Claims 12-13 (canceled)

Claim 14 (previously presented): The BGA package of claim 6, wherein the second bonding wire has one end electrically connected by a first trace to the corresponding via, and the other end electrically connected by a second trace to the corresponding bond finger.